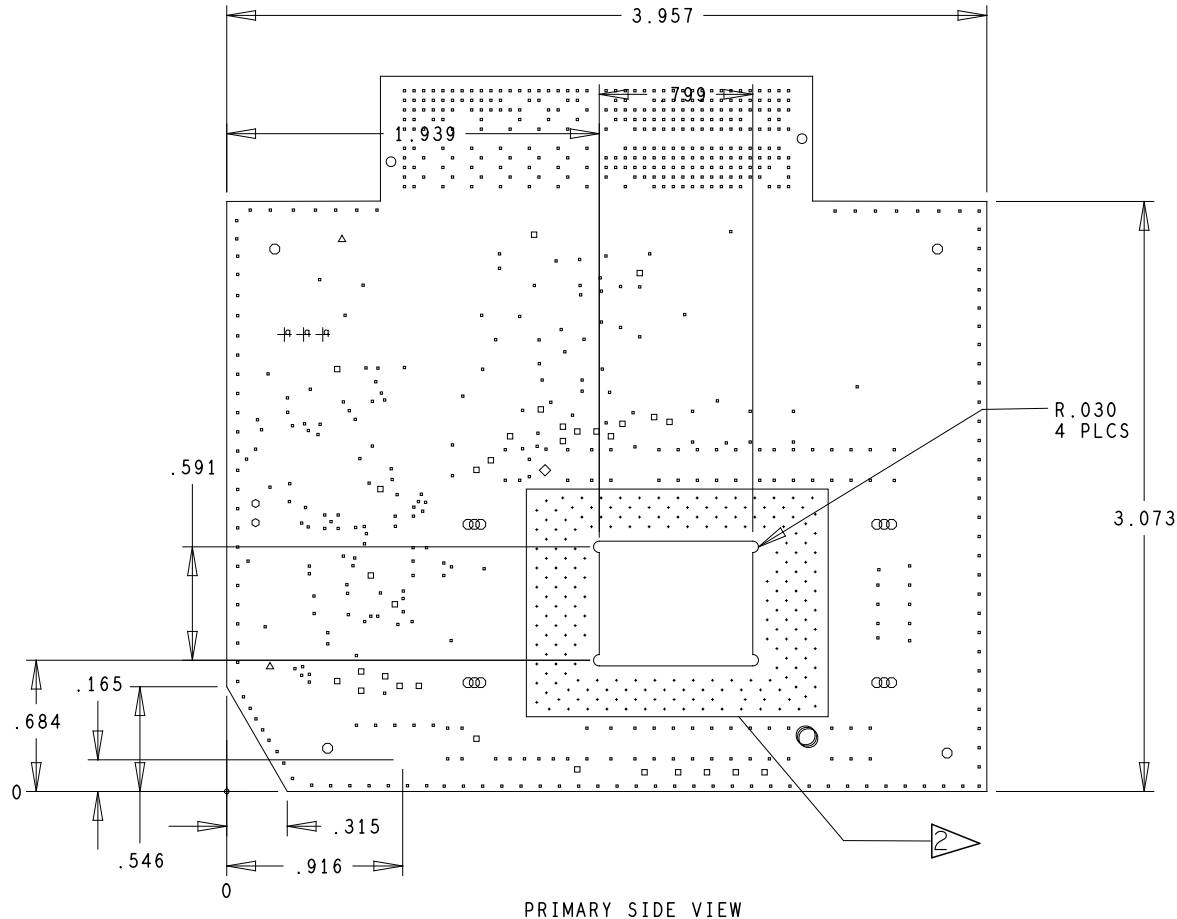


STACK-UP	MINIMUM FINAL COPPER WEIGHT			
LAYER 1 PRIMARY SIDE	1.5 OZ Cu			
LAYER 2 GND PLANE	1 OZ Cu			
LAYER 3 SIGNAL	.5 OZ Cu	4.25/6.75	100 OHMS DIFFERENTIAL	
LAYER 4 GND PLANE	1 OZ Cu			
LAYER 5 POWER PLANE	.5 OZ Cu			
LAYER 6 SIGNAL/GND	.5 OZ Cu	4.60/6.4	100 OHMS DIFFERENTIAL	
LAYER 7 GND PLANE	1 OZ Cu			
LAYER 8 SIGNAL	.5 OZ Cu	4.25/6.75	100 OHMS DIFFERENTIAL	
LAYER 9 GND PLANE	1 OZ Cu			
LAYER 10 SECONDARY SIDE	1.5 OZ Cu			

IMPEDANCE TOLERANCE = +/- 10%
ADJUST DIELECTRIC THICKNESS TO MEET SPECIFIED IMPEDANCE.



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	10.0	+3.0/-10.0	PLATED	202
*	12.0	+3.0/-12.0	PLATED	632
□	28.0	+3.0/-3.0	PLATED	31
⊕	40.0	+2.0/-2.0	PLATED	3
○	42.0	+3.0/-3.0	PLATED	2
△	63.0	+3.0/-3.0	PLATED	2
○	157.0	+3.0/-3.0	PLATED	16
○	50.0	+3.0/-3.0	NON-PLATED	2
◇	59.0	+3.0/-1.0	NON-PLATED	1
○	98.0	+3.0/-3.0	NON-PLATED	3

FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
- THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
- ALL BOARDS MUST MEET OR EXCEED UL94V-0 REQUIREMENTS. PCB MUST BEAR THE UL94V-0 UL-REGISTERED MATERIAL ID NUMBER.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
- OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.

PROCESS NOTES:

- EXCEPT AS NOTED IN NOTE 2, PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MICROINCHES THK GOLD 2-6 MICROINCHES THK.
- PLATE INDICATED AREAS OF DMD PADS WITH ELECTROLYTIC PLATING 100-200 MICRO-INCHES OF NICKEL UNDER 35-50 MICRO-INCHES OF GOLD.
- APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: GREEN. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
- FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. BOTH SIDES. COLOR: WHITE.

TEXAS INSTRUMENTS		
BOARD NAME:	DESCRIPTION: FABRICATION DRAWING	
PROJECT #: DLP084	DATE: 15 FEB 2023	REVISION: REV C